

R07DS0015EJ0100

Rev.1.00

Jul 01, 2010

NP33N06YDG

MOS FIELD EFFECT TRANSISTOR

The NP33N06YDG is N-channel MOS Field Effect Transistor designed for high current switching applications.

Features

- Low on-state resistance
 - R_{DS(on)} = 14 m Ω MAX. (V_{GS} = 10 V, I_D = 16.5 A)
- Low Ciss: Ciss = 2600 pF TYP. $(V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V})$
- Logic level drive type
- Designed for automotive application and AEC-Q101 qualified
- Small size package 8-pin HSON

Ordering Information

Part No.	LEAD PLATING	PACKING	Package
NP33N06YDG -E1-AY *1	Pure Sn (Tin)	Tape 2500 p/reel	8-pin HSON, Taping (E1 type)
NP33N06YDG -E2-AY *1			8-pin HSON, Taping (E2 type)

Note: *1. Pb-free (This product does not contain Pb in the external electrode.)

Absolute Maximum Ratings (T_A = 25°C)

Item	Symbol	Ratings	Unit
Drain to Source Voltage (V_{GS} = 0 V)	V _{DSS}	60	V
Gate to Source Voltage (V _{DS} = 0 V)	V _{GSS}	±20	V
Drain Current (DC) (T _C = 25°C)	I _{D(DC)}	±33	A
Drain Current (pulse) *1	I _{D(pulse)}	±66	A
Total Power Dissipation (T _C = 25°C)	P _{T1}	97	W
Total Power Dissipation ($T_A = 25^{\circ}C$) *2	P _{T2}	1.0	W
Channel Temperature	T _{ch}	175	°C
Storage Temperature	T _{stg}	–55 to +175	°C
Repetitive Avalanche Current *3	I _{AR}	16	A
Repetitive Avalanche Energy *3	E _{AR}	26	mJ

Thermal Resistance

Channel to Case Thermal Resistance	R _{th(ch-C)}	1.55	°C/W
Channel to Ambient Thermal Resistance *2	R _{th(ch-A)}	150	°C/W

Notes: *1. T_C = 25°C, PW \leq 10 μ s, Duty Cycle \leq 1%

- *2. Mounted on glass epoxy substrate of 40 mm x 40 mm x 0.8 mmt
- *3. $T_{ch(peak)} \leq 150^{\circ}C$, R_G = 25 Ω



Electrical Characteristics	(T _A = 25°C)
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ltem	Symbol	Min	Тур	Мах	Unit	Test Conditions
Zero Gate Voltage Drain Current	I _{DSS}			1	μA	V _{DS} = 60 V, V _{GS} = 0 V
Gate Leakage Current	I _{GSS}			±100	nA	V_{GS} = ±20 V, V_{DS} = 0 V
Gate to Source Threshold Voltage	V _{GS(th)}	1.4	1.8	2.5	V	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$
Forward Transfer Admittance *1	y _{fs}	13	26		S	V _{DS} = 5 V, I _D = 16.5 A
Drain to Source On-state	R _{DS(on)1}		11.2	14	mΩ	V _{GS} = 10 V, I _D = 16.5 A
Resistance ^{*1}	R _{DS(on)2}		12.8	20	mΩ	V _{GS} = 5 V, I _D = 16.5 A
Input Capacitance	C _{iss}		2600	3900	pF	V _{DS} = 25 V,
Output Capacitance	Coss		200	300	pF	V _{GS} = 0 V,
Reverse Transfer Capacitance	C _{rss}		120	220	pF	f = 1 MHz
Turn-on Delay Time	t _{d(on)}		16	32	ns	V _{DD} = 30 V, I _D = 16.5 A,
Rise Time	t _r		12	29	ns	V _{GS} = 10 V,
Turn-off Delay Time	t _{d(off)}		54	108	ns	R _G = 0 Ω
Fall Time	t _f		6	15	ns	
Total Gate Charge	Q _G		52	78	nC	V _{DD} = 48 V,
Gate to Source Charge	Q _{GS}		9		nC	V _{GS} = 10 V,
Gate to Drain Charge	Q _{GD}		16		nC	I _D = 33 A
Body Diode Forward Voltage *1	V _{F(S-D)}		0.9	1.5	V	I _F = 33 A, V _{GS} = 0 V
Reverse Recovery Time	t _{rr}		36		ns	I _F = 33 A, V _{GS} = 0 V,
Reverse Recovery Charge	Q _{rr}		47		nC	di/dt = 100 A/µs

PG.

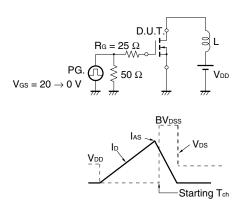
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Vgs

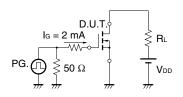
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Note: *1. Pulsed

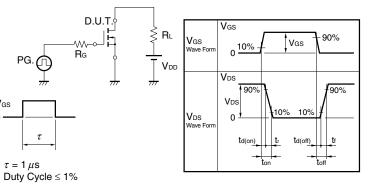
TEST CIRCUIT 1 AVALANCHE CAPABILITY



TEST CIRCUIT 3 GATE CHARGE



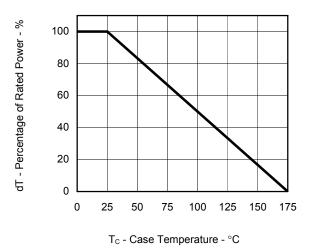
TEST CIRCUIT 2 SWITCHING TIME





Typical Characteristics (T_A = 25°C)

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



100 80 60 40 20 0 25 50 75 100 125 150 175 T_c - Case Temperature - °C

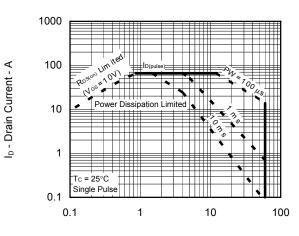
TOTAL POWER DISSIPATION vs.

CASE TEMPERATURE

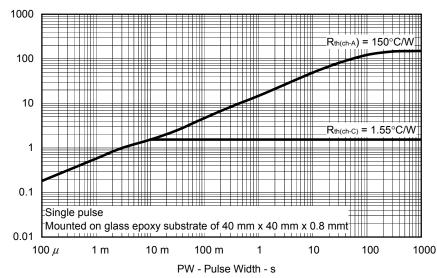
120

 $P_{\rm T}$ - Total Power Dissipation - W





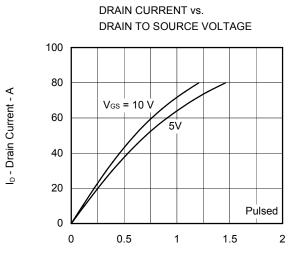




TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

 $r_{th(t)}$ - Transient Thermal Resistance - $^{\circ}\text{C/W}$

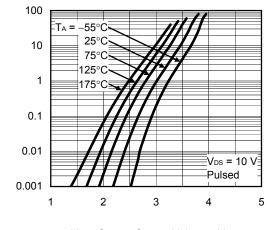


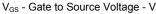


 V_{DS} - Drain to Source Voltage - V

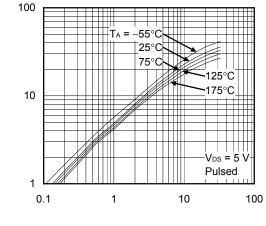
GATE TO SOURCE THRESHOLD VOLTAGE

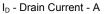
FORWARD TRANSFER CHARACTERISTICS



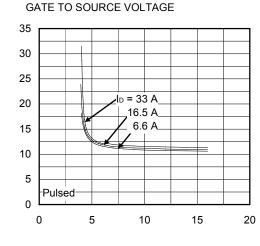


FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

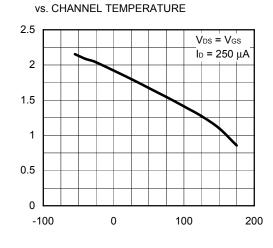




DRAIN TO SOURCE ON-STATE RESISTANCE vs.



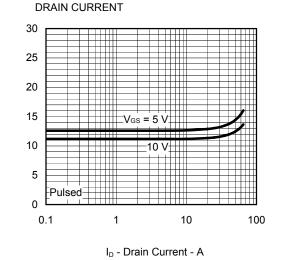
 V_{GS} - Gate to Source Voltage - V



 T_{ch} - Channel Temperature - $^{\circ}C$

DRAIN TO SOURCE ON-STATE RESISTANCE vs.





 $R_{\text{DS}(\text{on})}$ - Drain to Source On-state Resistance - $m\Omega$

I_D - Drain Current - A

y_{fs} | - Forward Transfer Admittance - S

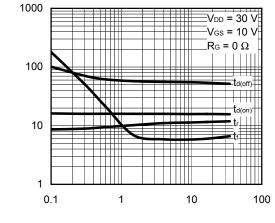


CHANNEL TEMPERATURE 40 I_D = 16.5 A 35 Pulsed 30 25 20 Vgs = 5 V 15 10 V 10 5 0 -100 0 100 200 T_{ch} - Channel Temperature - °C

DRAIN TO SOURCE ON-STATE RESISTANCE vs.

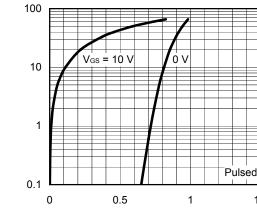






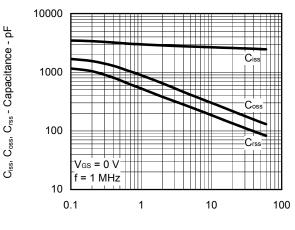
I_D - Drain Current - A

SOURCE TO DRAIN DIODE FORWARD VOLTAGE



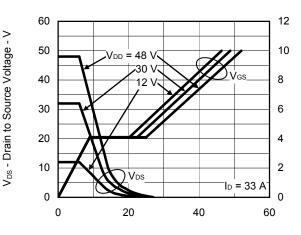


CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



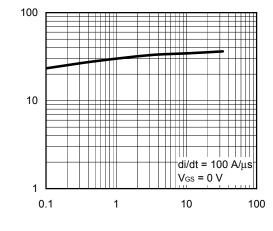
V_{DS} - Drain to Source Voltage - V





Q_G - Gate Charge - nC

REVERSE RECOVERY TIME vs. DRAIN CURRENT



IF - Drain Current - A

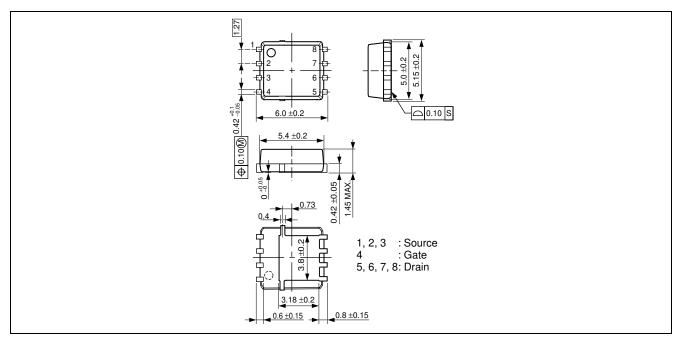
t_{olon}), t₁, t_{oloth}, t_r - Switching Time - ns R_{DS(on)} - Drain to Source On-state Resistance - mΩ

trr - Reverse Recovery Time - ns

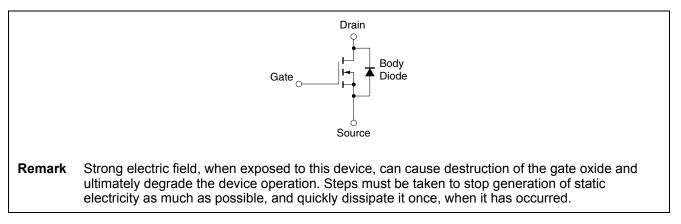
1.5

Package Drawings (Unit: mm)

8-pin HSON (Mass: 0.13 g TYP.)



Equivalent Circuit





Revision History	NP33N06YDG
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		Description		
Rev.	Date	Page	Summary	
1.00	Jul 01, 2010	-	First Eddition Issued	

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